

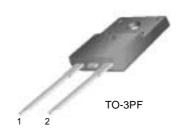
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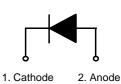
Features

- · High voltage and high reliability
- High speed switching
- · Low forward voltage

Applications

 Suitable for damper diode in horizontal deflection circuits





DAMPER DIODE

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Peak Repetitive Reverse Voltage	1700	V
I _{F(AV)}	Average Rectified Forward Current @ T _C = 125°C	10	Α
I _{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	А
T _{J,} T _{STG}	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics

Symbo	l Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	1.5	°C/W

Electrical Characteristics T_C=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V _{FM} *	Maximum Instantaneous Forward Voltage					V
	I _F = 10A	T _C = 25 °C T _C = 125 °C	-	-	2.2	
	I _F = 10A	T _C = 125 °C	-	-	2.0	
I _{RM} *	Maximum Instantaneous Reverse Current					mA
	@ rated V _R	$T_C = 25 ^{\circ}C$ $T_C = 125 ^{\circ}C$	-	-	0.1	
		T _C = 125 °C	-	-	10	
t _{rr}	Maximum Reverse Recovery Time		-	-	140	ns
	$(I_F = 1A, di/dt = 50A/\mu s)$					
t _{fr}	Maximum Forward Recovery Time		-	-	400	ns
	$(I_F = 6.5A, di/dt = 50A/\mu s)$					
V_{FRM}	Maximum Forward Recovery Voltage		-	-	13	V

^{*} Pulse Test: Pulse Width=300µs, Duty Cycle=2%

Typical Characteristics

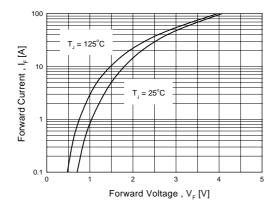


Figure 1. Typical Forward Voltage Drop vs. Forward Current

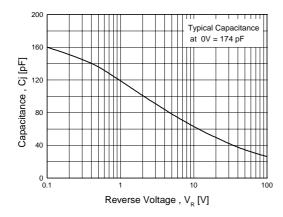


Figure 3. Typical Junction Capacitance

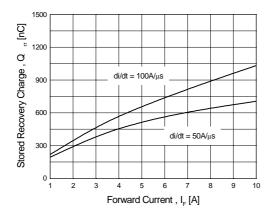


Figure 5. Typical Stored Charge vs. Forward Current

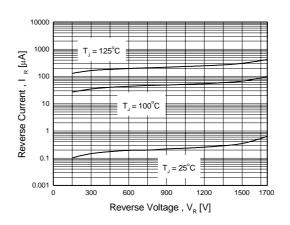


Figure 2. Typical Reverse Current vs. Reverse Voltage

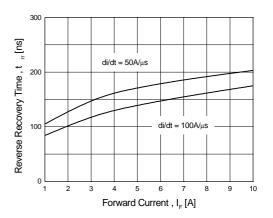


Figure 4. Typical Reverse Recovery Time vs. Forward Current

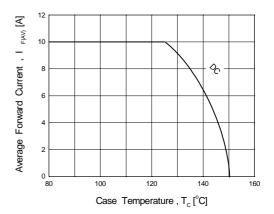
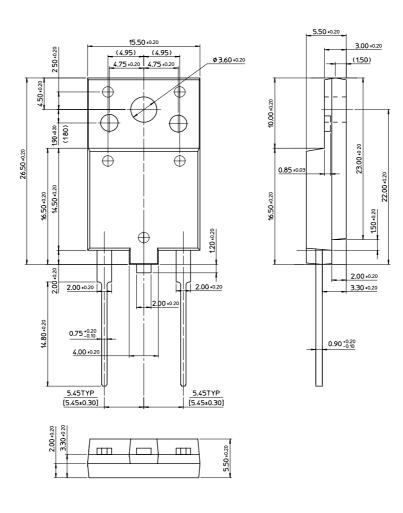


Figure 6. Forward Current Derating Curve

Package Dimensions

TO-3PF-2L



Dimensions in Millimeters

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